

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A carrier module, comprising:
 - a carrier module body for seating a semiconductor device on an underside thereof, having a pass through hole from an upper part to the underside where the semiconductor device is seated thereon;
 - a housing over the carrier module body;
 - a supplementary housing fitted in a lower part of the housing to be movable in up/down directions, for elastic contact with the carrier module body by a first elastic member fitted inside of the housing;
 - a vacuum tube in the supplementary housing so as to be in communication with the pass through hole in the carrier module body;
 - at least one pair of latches in a lower part of the carrier module body to move apart or close in an outer or inner side, for holding or releasing the semiconductor device seated on the carrier module body;
 - ~~a~~ at least one latch button fitted in an upper part of the carrier module body so as to be movable in up/down directions, and coupled to the ~~latch~~ at least one pair of latches with a

connection pin for moving in up/down directions by an external force, to ~~making move~~ the ~~latch to move~~ at least one pair of latches; and

a second elastic member for elastic supporting ~~[[of]]~~ the at least one latch buttons ~~button~~ on the carrier module body,

thereby, when the semiconductor device is brought into contact with ~~the~~ a test socket, and tested, ~~holding~~ the semiconductor device is held with a vacuum formed through the pass through hole in the carrier module body and the vacuum tube ~~in a state while the latch at~~ least one pair of latches releases the semiconductor device.

2. (Currently Amended) The carrier module as claimed in claim 1, further comprising a heat sink in a central part of the carrier module body, for ~~bringing being brought~~ into contact with a surface of the semiconductor device, and for transferring heat.

3. (Original) The carrier module as claimed in claim 1, further comprising an O-ring fitted at a connection part of the supplementary housing and the carrier module body.

4. (Currently Amended) The carrier module as claimed in claim 1, wherein the ~~latch~~ at least one pair of latches has a slanted slot of a long hole form for inserting a guide pin therein, wherein the ~~latch~~ at least one pair of latches is opened or closed, as the slanted slot slides along the guide pin.

5. (Currently Amended) The carrier module as claimed in claim 1, wherein the at least one pair of latches further comprising comprise:

~~a latch pusher projected upward from one side part of the test socket to be brought into contact with the semiconductor device; and~~

a projection projected outwardly from an outer part of ~~the each latch, for being~~ wherein the projection is configured to be brought into contact with the a latch pusher on the test socket to thereby open each latch.

6. (New) A carrier module, comprising:

a housing having an internal accommodating space;

a supplemental housing that is partially accommodated in the internal accommodating space of the housing and having a vacuum tube; and

a carrier module body having a latch and a through hole, wherein one end of the through hole seats a semiconductor device and is configured to hold the semiconductor device with a vacuum, and the other end of the through hole is aligned and communicates with the vacuum tube.

7. (New) The carrier module of claim 6, wherein a first elastic member is further accommodated in the internal accommodating space of the housing and elastically supports the supplemental housing.

8. (New) The carrier module of claim 7, wherein the supplementary housing includes an annular pusher formed around the supplementary housing for receiving support from the first elastic member.

9. (New) The carrier module of claim 8, wherein the housing includes an annular projection for seating the annular pusher of the supplemental housing.

10. (New) The carrier module of claim 6, wherein the vacuum tube and the through hole are configured to keep a vacuum when mated.

11. (New) The carrier module of claim 10, wherein an O-ring is fitted to one of an end of the vacuum tube and an end of the through hole, to thereby keep the vacuum.

12. (New) The carrier module of claim 11, wherein the O-ring is fitted to an end of the vacuum tube.

13. (New) The carrier module of claim 6, wherein the carrier module body further includes a heat sink for at least one of heating, and dissipating heat from, a semiconductor device seated on the carrier module.

14. (New) The carrier module of claim 13, wherein the through hole is formed through the heat sink.

15. (New) A carrier module, comprising:
a telescoping housing having a first internal vacuum conduit; and
a carrier module having a latch and a second internal vacuum conduit having a first and a second end, wherein the first internal vacuum conduit is in vacuum communication with the first end of the second internal conduit, and wherein both the latch and the second end of the second internal conduit are configured to hold a semiconductor device.

16. (New) The carrier module of claim 15, wherein the first internal vacuum conduit of the telescoping housing and the second internal vacuum conduit of the carrier module are fitted to form a continuous vacuum conduit.

17. (New) The carrier module of claim 15, wherein the second vacuum conduit is formed by a heat sink formed through the carrier module, and a first end of the heat sink contacts the first vacuum conduit and a second end of the heat sink is configured to contact a semiconductor device.

18. (New) The carrier module of claim 15, further comprising a latch button which is slidably fitted to the carrier module; and

a guide pin fixed to the carrier module, wherein the latch further comprises an elongated slanted hole that accommodates the guide pin and pivots about a connection pin attached to the latch button, so that when the latch button is moved, the latch pivots about the connection pin while the guide pin guides the movement of the slanted hole to open the latch.

19. (New) The carrier module of claim 18, wherein the latch further comprises a projection for contact with a latch pusher of a test socket.

20. (New) The carrier module of claim 15, wherein the presence of the semiconductor device on the second end of the second internal conduit is determined by the presence of a vacuum formed in the first and second internal conduits.